



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-04-21
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	LAURENT TOSI	Representative Title	MDG MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H743IIK6	P0MR*450XXXY	A	9996	2017-04-21
	Amount	UoM	Unit type	ST ECOPACK Grade
	111.20	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
SOLDERBALL (Sn96.5Ag3.5)	NAC	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	10x10x0.6	201	No lead	
Comment	Package: A0E7 UFBGA 10X10X0.6 176+25 P0.65 8249558			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	POMR*450XXXY									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	4.802	mg	supplier	die	Silicon (Si)	7440-21-3		4.050	mg	845481	36511				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	18326	791				
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	57476	2482				
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	208	9				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	9371	405				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	1666	72				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	208	9				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	67264	2905				
				supplier	CORE	Glass Cloth	65997-17-3		3.567		84900	32073				
				supplier	CORE	Epoxy resin	61788-97-4		0.840		20000	7556				
SUBSTRATE (DS7409HGB)	Other inorganic materials	42.009	mg	supplier	CORE	Flame resistant epoxy resin	223769-10-6		0.840		20000	7556				
				supplier	CORE	Heat resistant resin	25722-66-1		0.840		20000	7556				
				supplier	CORE	Silica filler	7631-86-9		2.096		49900	18851				
				supplier	CORE	Metal Hydroxide	Trade secret		0.210		5000	1889				
				supplier	COPPER FOIL	Copper (Cu)	7440-50-8		8.389		199700	75442				
				supplier	SOLDERMASK	Talc containing no asbestiform fibers	14807-96-6		0.256		6100	2304				
				supplier	SOLDERMASK	Barium sulfate	7727-43-7		4.134		98400	37173				
				supplier	SOLDERMASK	Dipropylene monomethyl ether	34590-94-8		1.222		29100	10993				
				supplier	SOLDERMASK	Napthalene	91-20-3		0.126		3000	1133				
				supplier	SOLDERMASK	Morpholine derivative	Trade secret		0.630		15000	5667				
				supplier	CU PLATING	Copper (Cu)	7440-50-8		16.157		384600	145294				
				supplier	NI PLATING	Nickel (Ni)	7440-02-0		2.416		57500	21722				
				supplier	AU PLATING	Gold (Au)	7440-57-5		0.286		6800	2569				
				DIE ATTACH (ATB-130U)	Other inorganic materials	1.267	mg	supplier	GLUE	Butadiene,acrylonitrile polymer,carboxy-termi	68610-41-3		0.887		700000	7973
								supplier	GLUE	Phenol-formaldehyde polymer	9003-35-4		0.127		100000	1139
supplier	GLUE	Phenol polymer with formaldehyde,glycidyl et	28064-14-4						0.117		92000	1048				
supplier	GLUE	Dapson	80-08-0						0.123		97000	1105				
supplier	GLUE	Reaction product bisphenol-A-(epichlorhydrin	25068-38-6						0.013		10000	114				
supplier	GLUE	4,4, Isopropylidenediphenol	80-05-7						0.001		1000	11				
BONDING WIRE (MKE 4N)	Other inorganic materials	3.122	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		3.122		1000000	28079				
SOLDERBALL (Sn96.5Ag3.5)	Other inorganic materials	6.241	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		6.023		965007	54163				
				supplier	SOLDERBALL	Silver (Ag)	7440-22-4		0.218		34993	1964				
ENCAPSULATION (GE-100LFC5)	Other inorganic materials	53.759	mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		48.309		898619	434430				
				supplier	MOLDING COMPOUND	Epoxy resin	Trade secret		2.453		45621	22055				
				supplier	MOLDING COMPOUND	Phenol resin	Trade secret		2.180		40552	19605				
				supplier	MOLDING COMPOUND	Metal Hydroxide	Trade secret		0.545		10138	4901				
				supplier	MOLDING COMPOUND	Carbon black	1333-86-4		0.273		5069	2451				